

FEATURES

- Double Side Cooling
- High Reliability In Service
- High Voltage Capability
- Fault Protection Without Fuses
- High Surge Current Capability
- Turn-off Capability Allows Reduction in Equipment Size and Weight. Low Noise Emission Reduces Acoustic Cladding Necessary For Environmental Requirements

APPLICATIONS

- Variable speed AC motor drive inverters (VSD-AC) including Traction drives
- Uninterruptable Power Supplies
- High Voltage Converters
- Choppers
- Welding
- Induction Heating
- DC/DC Converters

KEY PARAMETERS

I_{TCM}	3000A
V_{DRM}	4500V
$I_{T(AV)}$	780A
dV_D/dt^*	1000V/μs
dl_T/dt	400A/μs

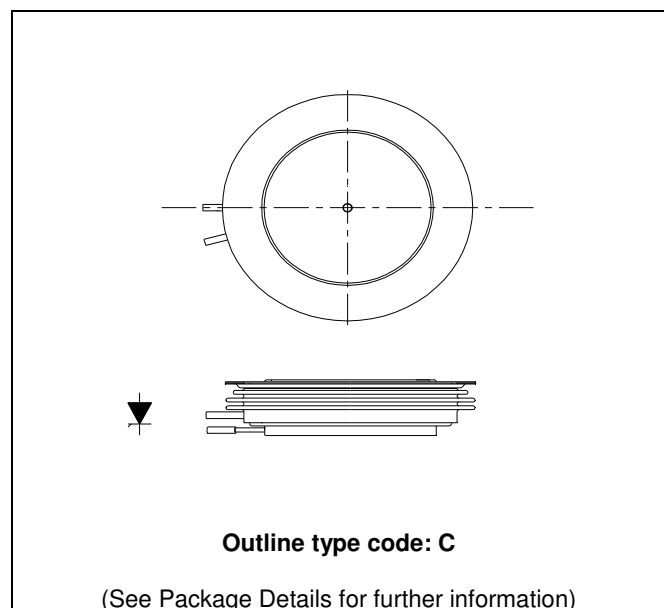


Fig. 1 Package outline

VOLTAGE RATINGS

Type Number	Repetitive Peak Off-state Voltage V_{DRM} (V)	Repetitive Peak Reverse Voltage V_{RRM} (V)	Conditions
DG808BC45	4500	16	$T_{vj} = 125^{\circ}C$, $I_{DM} = 100mA$, $I_{RRM} = 50mA$

CURRENT RATINGS

Symbol	Parameter	Conditions	Max.	Units
I_{TCM}	Repetitive peak controllable on-state current	$V_D = 66\%V_{DRM}$, $T_j = 125^{\circ}C$, $dl_{GQ}/dt = 40A/\mu s$, $C_S = 4 \mu F$	3000	A
$I_{T(AV)}$	Mean on-state current	$T_{HS} = 80^{\circ}C$, Double side cooled. Half sine 50Hz	780	A
$I_{T(RMS)}$	RMS on-state current	$T_{HS} = 80^{\circ}C$, Double side cooled. Half sine 50Hz	1225	A

SURGE RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
I_{TSM}	Surge (non repetitive) on-state current	10ms half sine. $T_j = 125^\circ\text{C}$	16.0	kA
I^2t	I^2t for fusing	10ms half sine. $T_j = 125^\circ\text{C}$	1.28	MA^2s
di_T/dt	Critical rate of rise of on-state current	$V_D = 3000\text{V}$, $I_T = 3000\text{A}$, $T_j = 125^\circ\text{C}$, $I_{FG} > 40\text{A}$, Rise time $> 1.0 \mu\text{s}$	400	$\text{A}/\mu\text{s}$
dV_D/dt	Rate of rise of off-state voltage	To 66% V_{DRM} ; $R_{GK} \leq 1.5\Omega$, $T_j = 125^\circ\text{C}$	100	$\text{V}/\mu\text{s}$
		To 66% V_{DRM} ; $V_{RG} \leq -2\text{V}$, $T_j = 125^\circ\text{C}$	1000	$\text{V}/\mu\text{s}$
L_S	Peak stray inductance in snubber circuit	$I_T = 3000\text{A}$, $V_D = V_{DRM}$, $T_j = 125^\circ\text{C}$, $dI_{GQ} = 40\text{A}/\mu\text{s}$, $C_S = 4.0\mu\text{F}$	200	nH

GATE RATINGS

Symbol	Parameter	Test Conditions	Min.	Max.	Units
V_{RGM}	Peak reverse gate voltage	This value may exceeded during turn-off	-	16	V
I_{FGM}	Peak forward gate current		-	100	A
$P_{FG(AV)}$	Average forward gate power		-	20	W
P_{RGM}	Peak reverse gate power		-	24	kW
di_{GQ}/dt	Rate of rise of reverse gate current		30	60	$\text{A}/\mu\text{s}$
$t_{ON(min)}$	Minimum permissible on time		50	-	μs
$t_{OFF(min)}$	Minimum permissible off time		100	-	μs

THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions	Min.	Max.	Units	
$R_{th(j-hs)}$	Thermal resistance – junction to heatsink surface	Double side cooled	DC	-	0.014	$^\circ\text{C}/\text{W}$
		Single side cooled	Anode DC	-	0.0233	$^\circ\text{C}/\text{W}$
			Cathode DC	-	0.035	$^\circ\text{C}/\text{W}$
$R_{th(c-hs)}$	Contact thermal resistance	Clamping force 36.0kN With mounting compound	Per contact	-	0.0036	$^\circ\text{C}/\text{W}$
T_{vj}	Virtual junction temperature	On-state (conducting)		-40	125	$^\circ\text{C}$
T_{op}/T_{stg}	Operating junction/storage temperature range			-40	125	$^\circ\text{C}$
F_m	Clamping force			28.0	44.0	kN

CHARACTERISTICS
T_j = 125°C unless stated otherwise

Symbol	Parameter	Test Conditions	Min.	Max.	Units
V _{TM})	On-state voltage	At 3000A peak, I _{G(ON)} = 10A d.c.	-	3.75	V
I _{DM}	Peak off-state current	V _{DRM} = 4500V, V _{RG} = 0V	-	100	mA
I _{RRM}	Peak reverse current	V _{RRM} = 16V	-	50	mA
V _{GT}	Gate trigger voltage	V _D = 24V, I _T = 100A, T _j = 25°C	-	1.2	V
I _{GT}	Gate trigger current	V _D = 24V, I _T = 100A, T _j = 25°C	-	3.5	A
I _{RGM}	Reverse gate cathode current	V _{RGM} = 16V, No gate/cathode resistor	-	10	mA
E _{ON}	Turn-on Energy	V _D = 3000V	-	2860	mJ
t _d	Delay time	I _T = 3000A, dI _T /dt = 300A/μs	-	2.1	μs
t _r	Rise time	I _{FG} = 40A, rise time < 1.0μs	-	4.8	μs
E _{OFF}	Turn-off energy	I _T = 3000A, V _{DM} = V _{DRM} Snubber Cap C _s = 4.0μC di _{GQ} /dt = 40A/us	-	12000	mJ
t _{gs}	Storage time		-	25	μs
t _{gf}	Fall time		2	μs	
t _{gq}	Gate controlled turn-off time		-	27	μs
Q _{GQ}	Turn-off gate charge		12000	μC	
Q _{GQT}	Total turn-off gate charge		24000	μC	
I _{GQM}	Peak reverse gate current		-	800	A

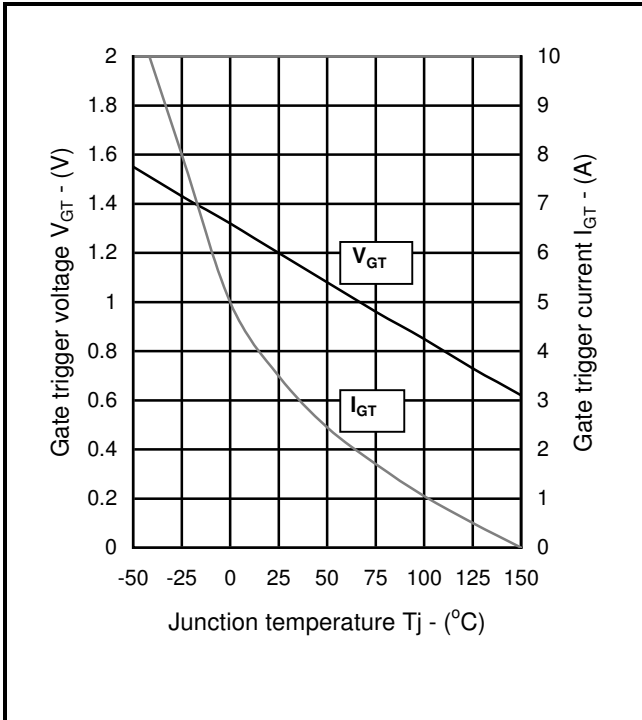


Fig.2 Maximum gate trigger voltage/current vs junction temperature

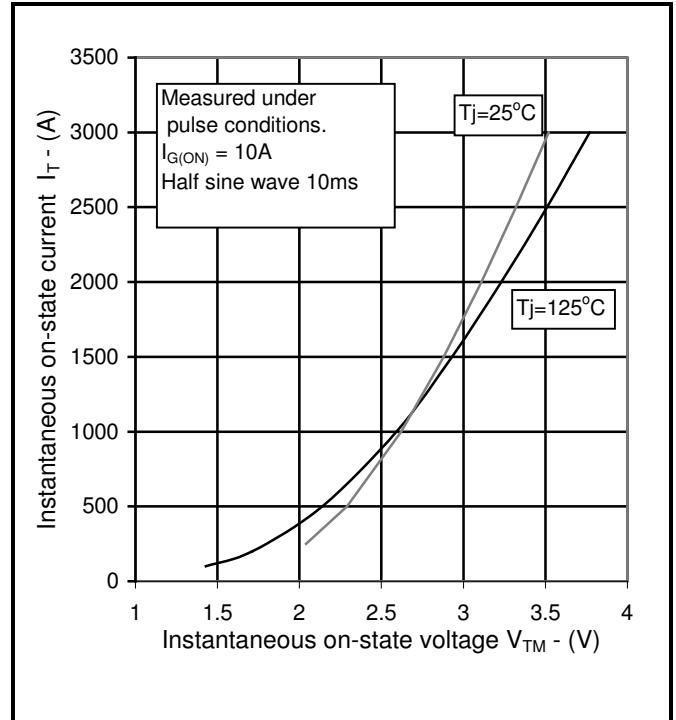


Fig.3 On-state characteristics

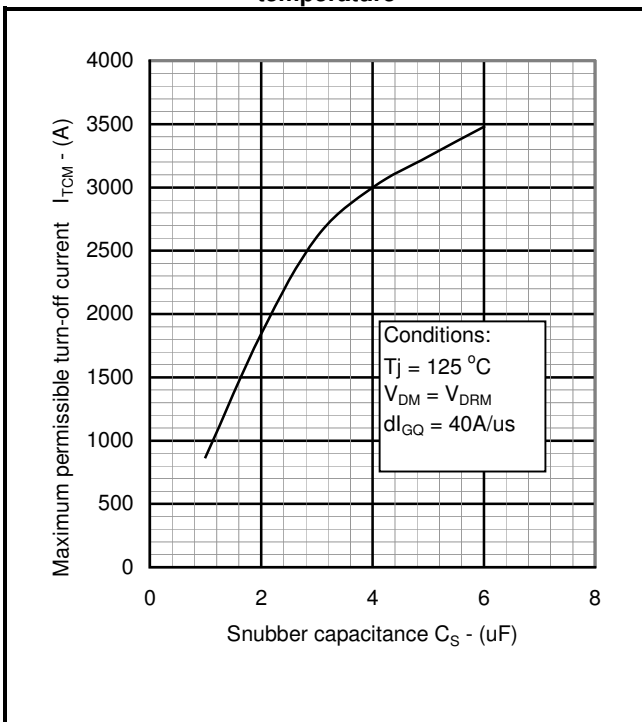


Fig.4 Maximum dependence of I_{TCM} on C_S

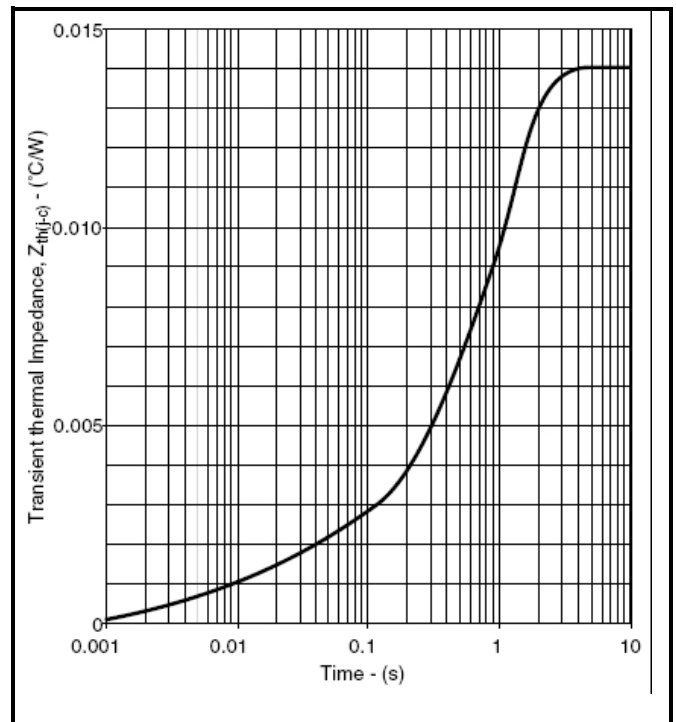


Fig.5 Maximum (limit) transient thermal impedance-double side cooled

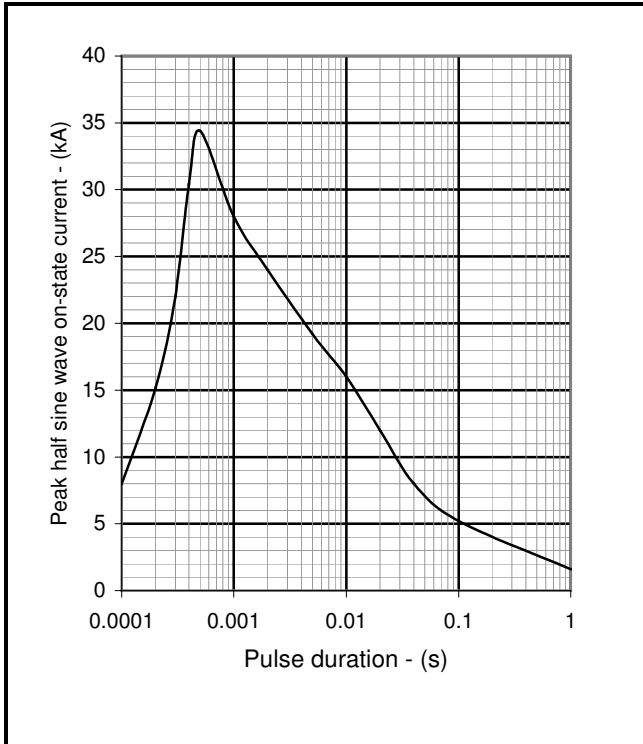


Fig.6 Surge (non-repetitive) on-state current vs time

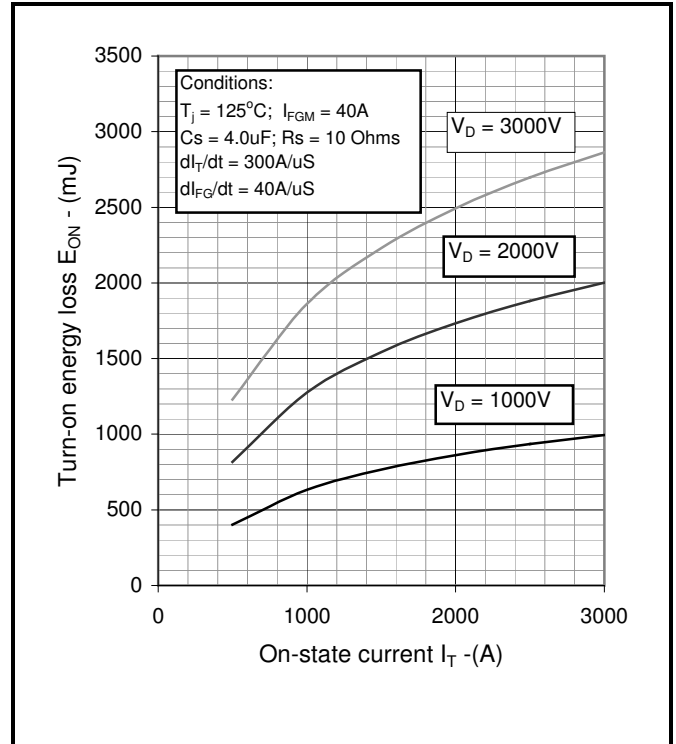


Fig.7 Turn-on energy vs on-state current

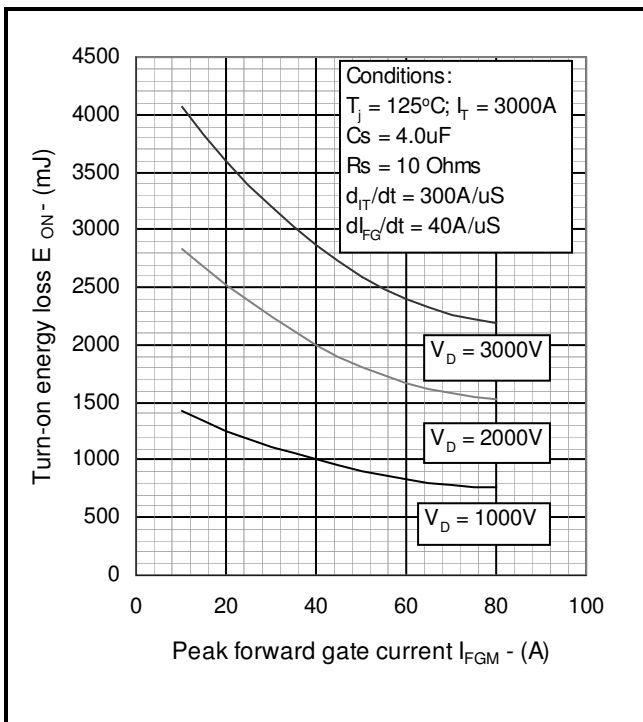


Fig.8 Turn-on energy vs forward gate current

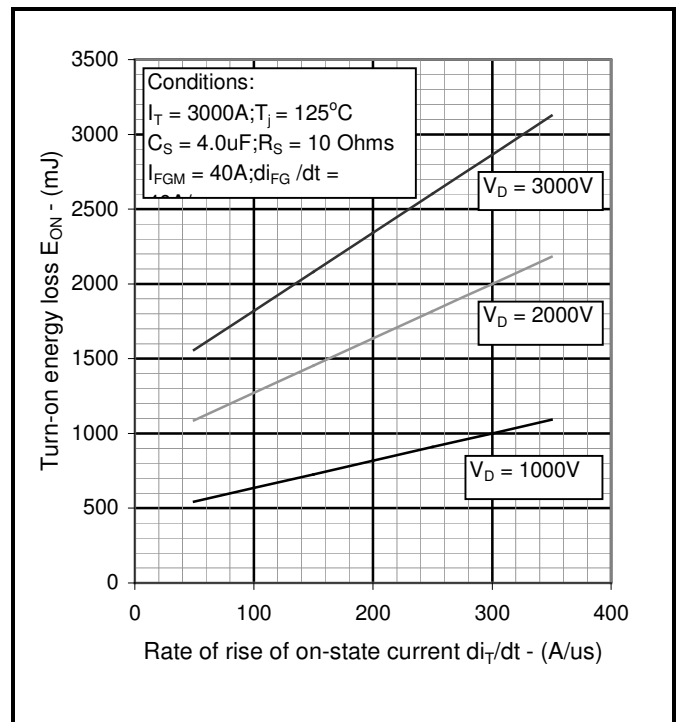


Fig.9 Turn-on energy vs rate of rise of on-state current

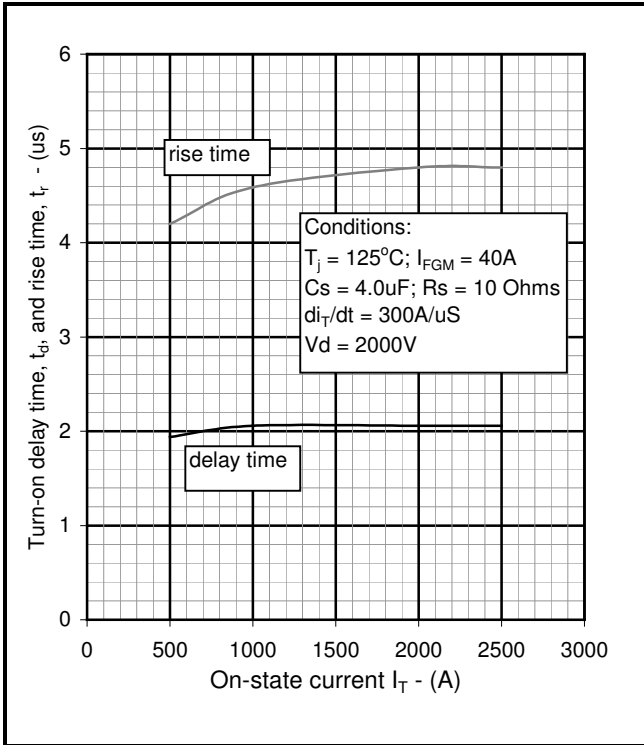


Fig.10 Delay and rise time vs on-state current

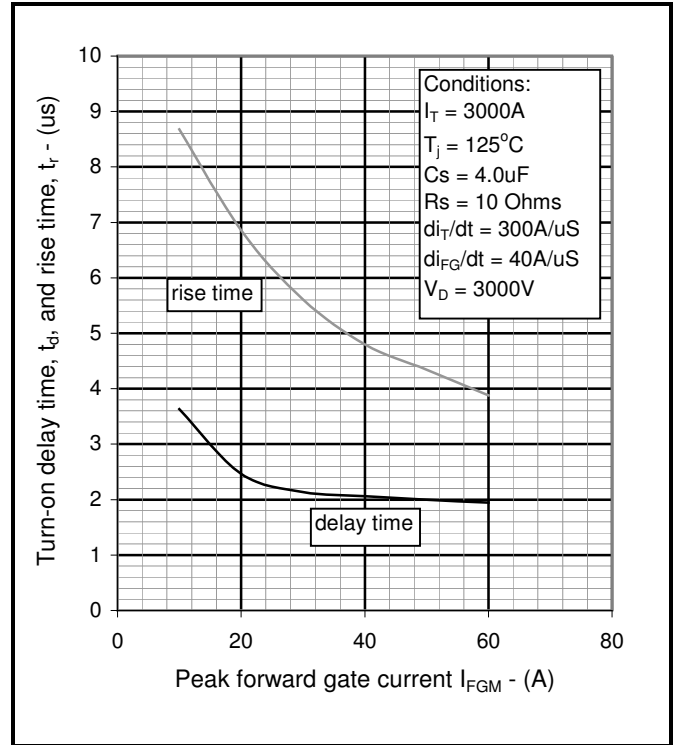


Fig.11 Delay and rise time vs peak forward gate current

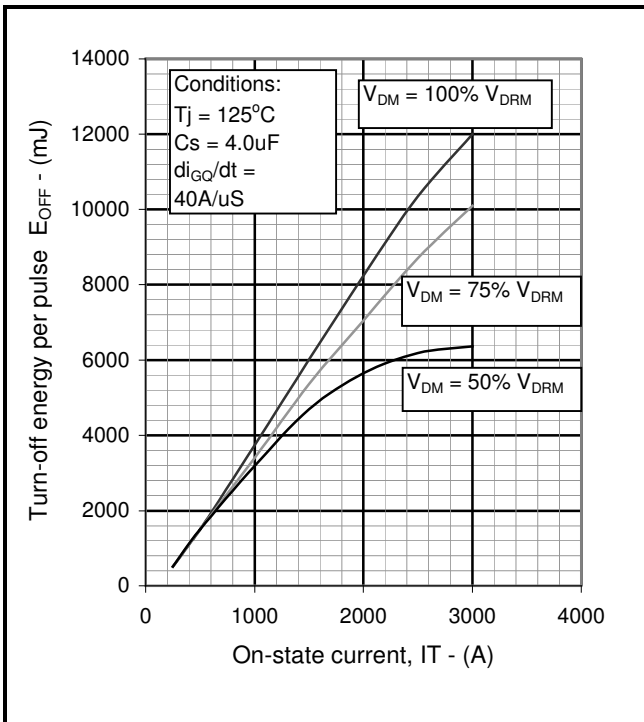


Fig.12 Turn-off energy vs on-state current

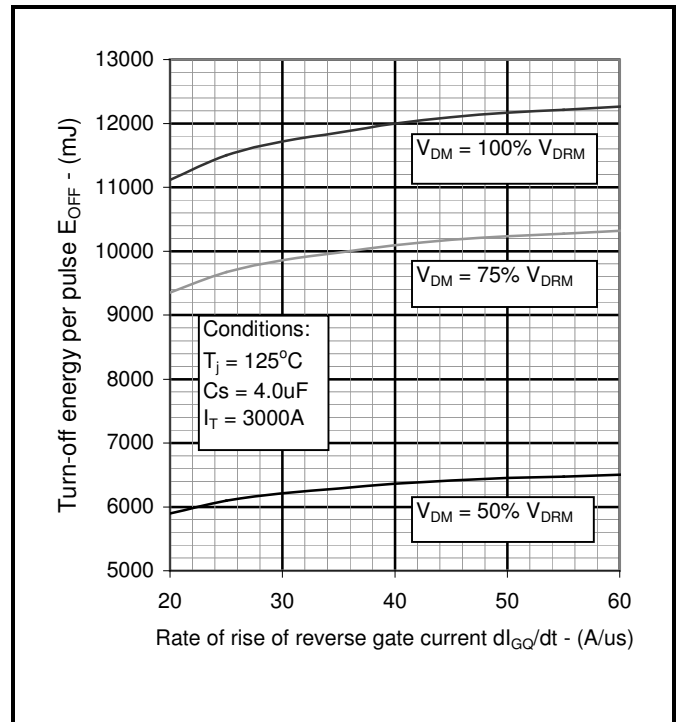


Fig.13 Turn-off energy loss vs rate of rise of reverse gate current

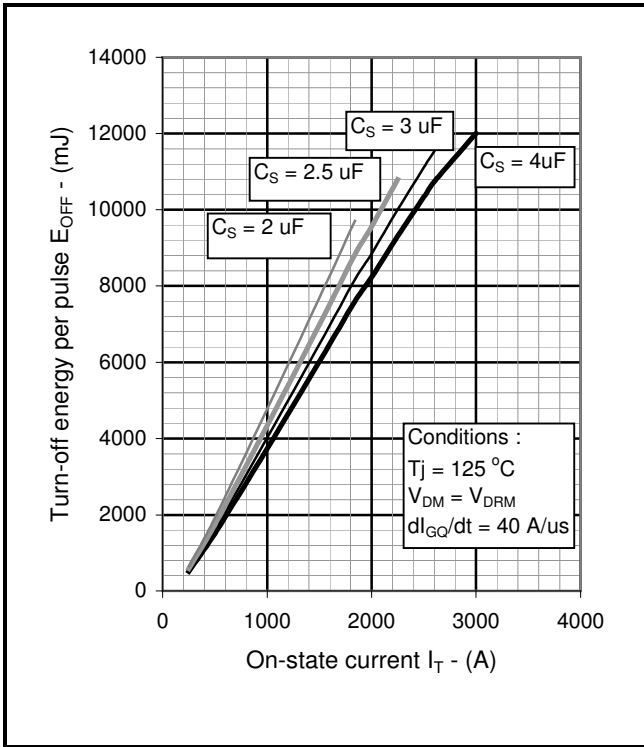


Fig.14 Turn-off energy vs on-state current

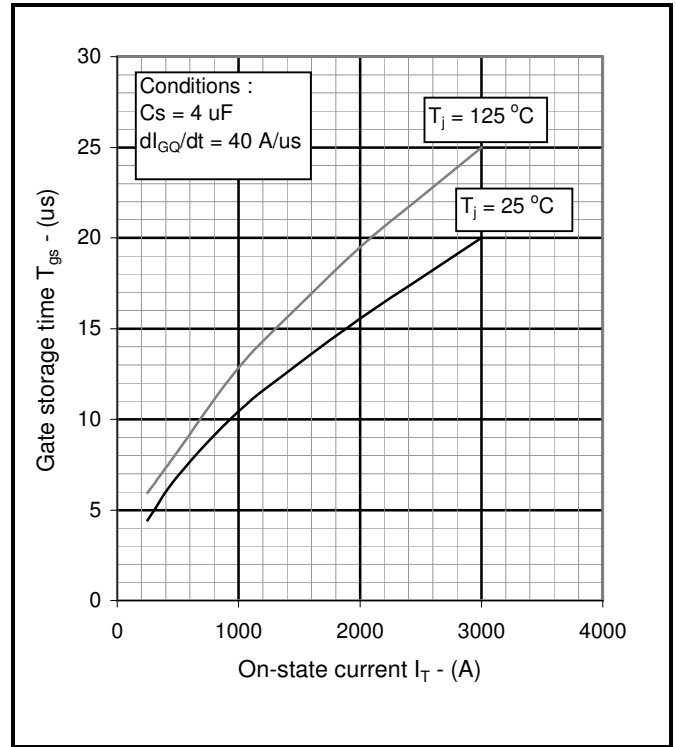


Fig.15 Gate storage time vs on-state current

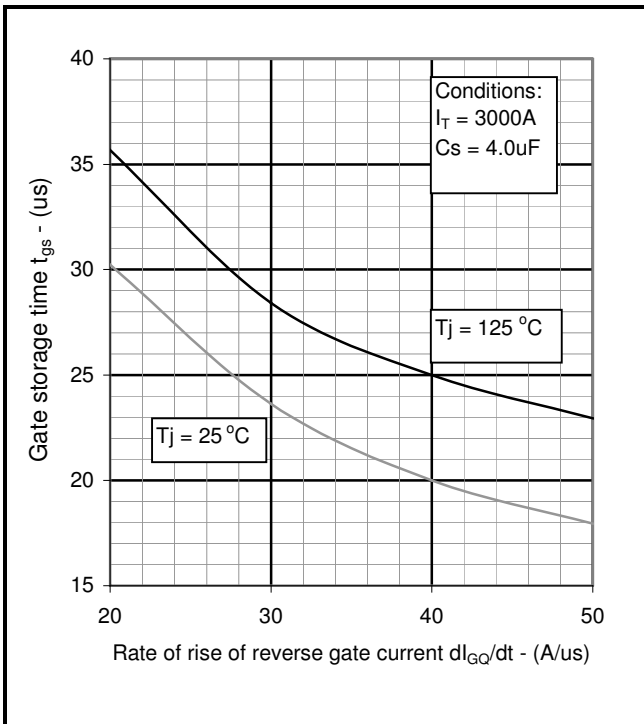


Fig.16 Gate storage time vs rate of rise of reverse gate current

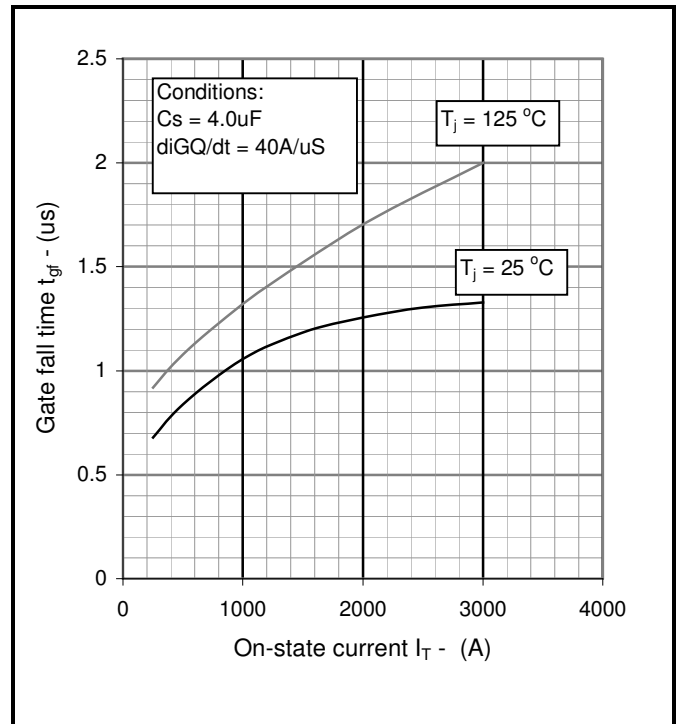


Fig.17 Gate fall time vs on-state current

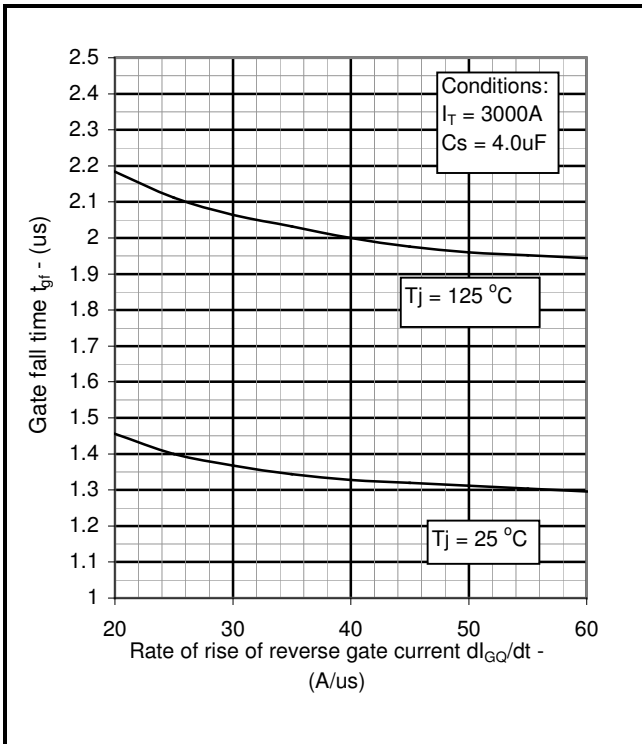


Fig.18 Gate fall time vs rate of rise of reverse gate current

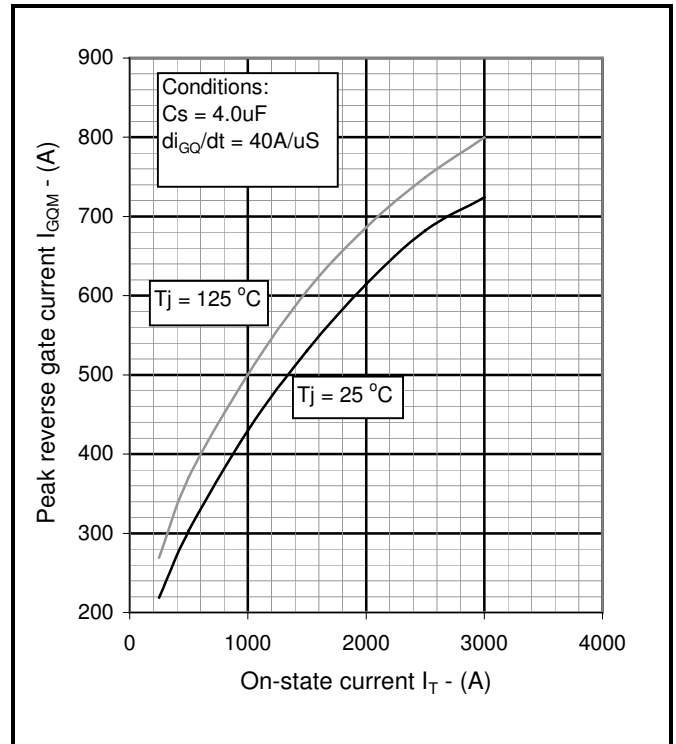


Fig.19 Peak reverse gate current vs on-state current

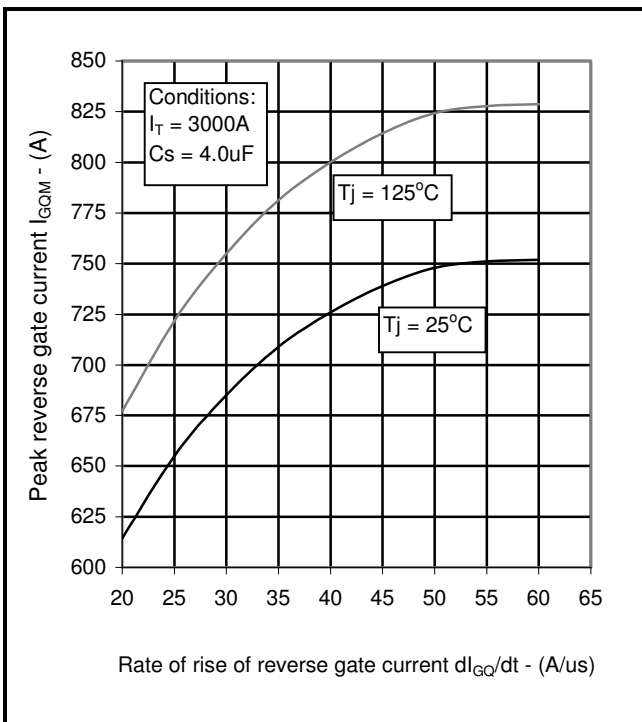


Fig.20 Reverse gate current vs rate of rise of reverse gate current

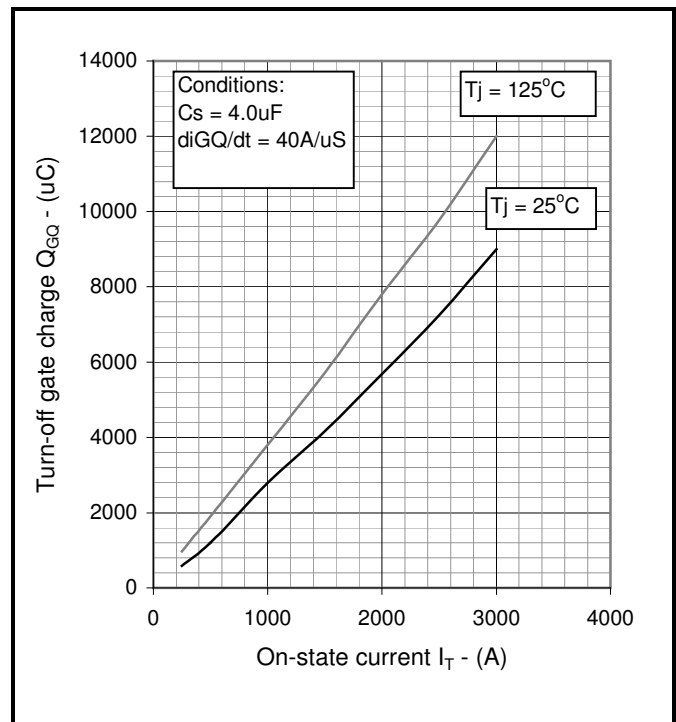


Fig.21 Turn-off gate charge vs on-state current

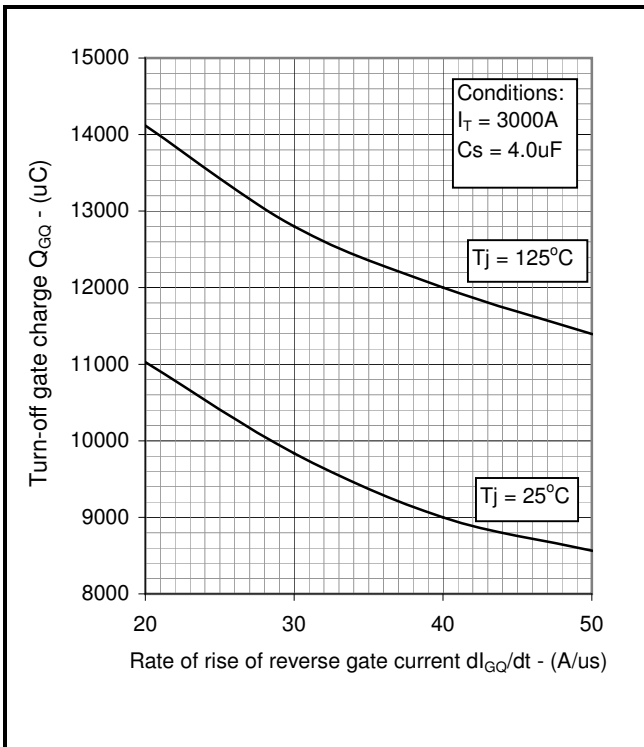


Fig.22 Turn-off charge vs rate of rise of reverse gate current

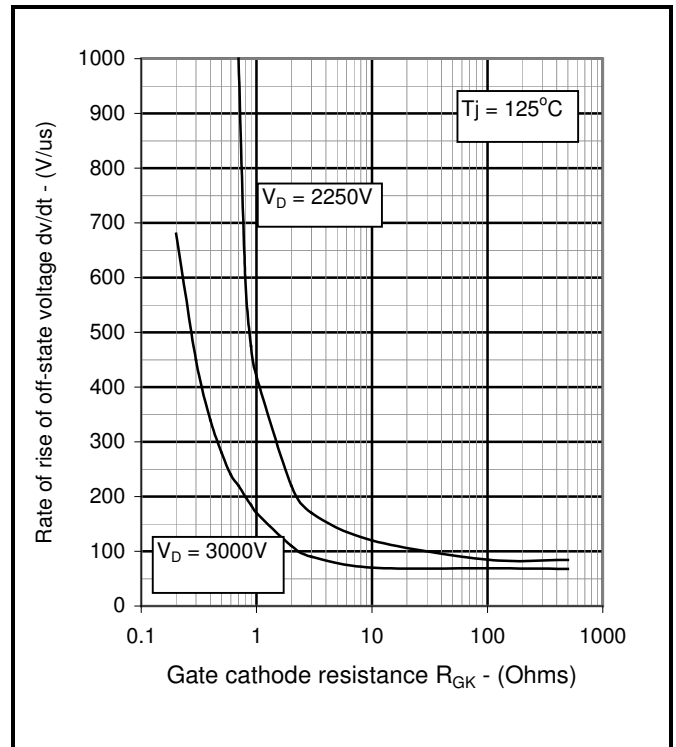
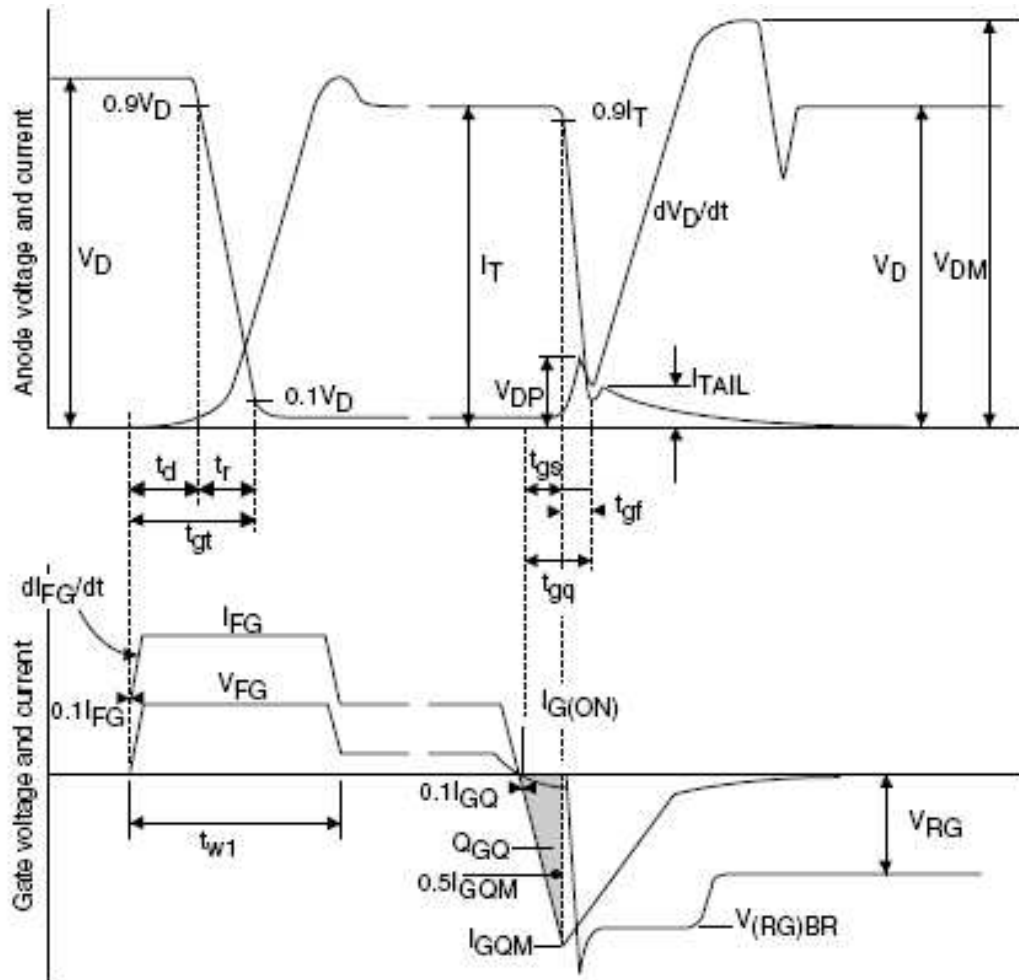


Fig.23 Rate of rise of off-state voltage vs gate cathode resistance



Recommended gate conditions:

- $I_{TCM} = 1000A$
- $I_{FG} = 30A$
- $I_{G(ON)} = 4A$ d.c.
- $t_{w1(min)} = 10\mu s$
- $I_{GQM} = 420A$
- $dI_{GQ}/dt = 30A/\mu s$
- $Q_{GQ} = 3000\mu C$
- $V_{RG(min)} = 2V$
- $V_{RG(max)} = 16V$

These are recommended Dynex Semiconductor conditions. Other conditions are permitted according to users gate drive specifications.

Fig.24 General switching waveforms

PACKAGE DETAILS

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.

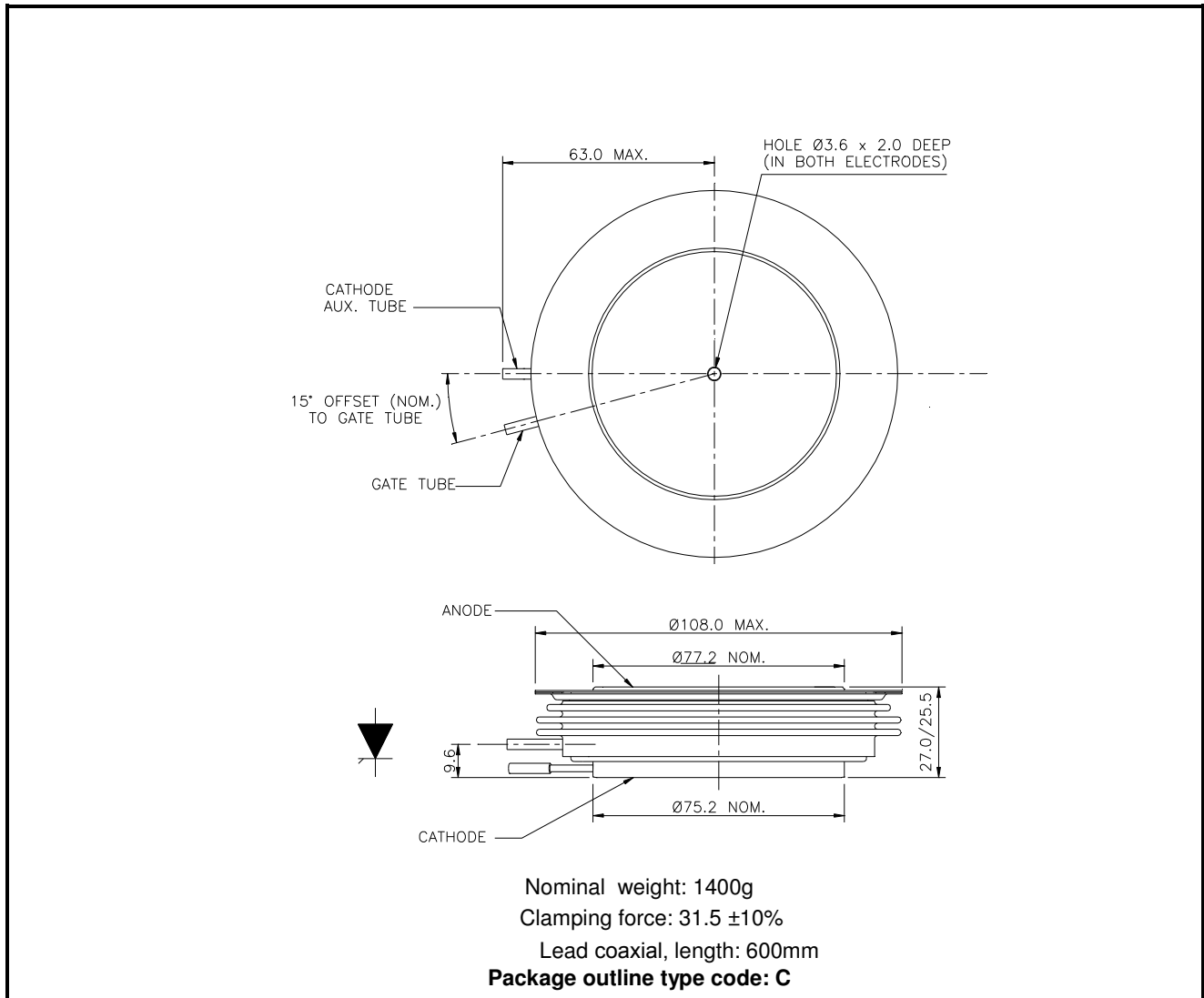


Fig.31 Package outline



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